AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method for manufacturing a USB electronic key, ~~whereby~~ comprising cutting out a microcircuit ~~is cut out~~ from a tape having a plurality of microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; said method further comprising ~~the following step whereby~~, in a single operation, adjusting the thickness of the microcircuit ~~is adjusted~~ at least in the area of the contact pads, so as to have a thickness that conforms to the USB Standard.

2. (Currently Amended) A manufacturing method according to claim 1, wherein the ~~adjustment is achieved by~~ adjusting comprises disposing a casing comprising at least one bottom half-shell ~~disposed~~ at least under the contact pads.

3. (Currently Amended) A manufacturing method according to claim 2, ~~wherein~~ further comprising interfitting the bottom half-shell ~~is interfitted~~ with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.

4. (Currently Amended) A manufacturing method according to claim 1, wherein the ~~adjustment is achieved by~~ adjusting comprises inserting the microcircuit into a shell having an access on a rear edge.

5. (Currently Amended) A manufacturing method according to claim 1, wherein the ~~adjustment is achieved by~~ adjusting comprises forming an overmolded portion over the microcircuit.

6. (Currently Amended) A manufacturing method according to claim 1, ~~wherein~~ further comprising fastening the microcircuit ~~is fastened~~ to the bottom half-shell.

7. (Currently Amended) A manufacturing method according to claim 6, wherein the ~~microcircuit~~ fastening is ~~fastened~~ by adhesive bonding or by tight-fitting cross-wise at least.

8. (Previously Presented) A manufacturing method according to claim 1, wherein the electronic component is disposed at a location offset from a location of the contact pads.

9. (Previously Presented) A manufacturing method according to claim 1, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10. (Withdrawn) An electronic key including a microcircuit defining USB-format contact pads and carrying at least one electronic component connected to the pads, wherein the contact pads are disposed on a dielectric having a thickness of

less than 200 µm; and its thickness is adjusted by portion of material overmolded over the microcircuit, at least in the area of and below a location of the contact pads, so that its microcircuit thickness conforms to the USB Standard.

11. (Withdrawn) An electronic key according to claim 10, wherein the overmolded portion is suitable for subsequently receiving a covering.

12. (Withdrawn) An electronic key comprising a microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, wherein the contact pads are disposed on a dielectric having a thickness of less than 200 µm; and its microcircuit thickness is adjusted by a bottom shell, at least in the area of a location of the contact pads, so that its microcircuit thickness conforms to the USB Standard.

13. (Withdrawn) An electronic key according to claim 11, wherein the bottom half-shell is interfitted with a top half-shell which covers a zone of the microcircuit that lies outside the location of the contact pads.

14. (Withdrawn) An electronic key according to claim 12, wherein it has an access for inserting the microcircuit on a rear edge of its shell.